

33rd IEEE Conference on Electrical Performance of Electronic Packaging and Systems



EPEPS is the premier international conference on advanced and emerging issues in the electrical modeling, analysis, and design of electronic interconnections, packages, and systems. Over four days, the conference will feature the latest advancements in modeling, design, and measurement techniques for SI, PI, and performance optimization in high-speed, RF, wireless and quantum systems.

EPEPS 2024 will be held in the gorgeous city of Toronto, the fastest growing tech hub in North America, close to prominent microelectronic companies, and home to a large talent pool of 400,000+ post-secondary students.

We look forward to seeing you in Toronto!
Piero Triverio & Wendem Beyene

Call for papers

We welcome new and unpublished contributions on:

Interconnects design & technologies

- High-speed channels, backplanes, SerDes, memory, DDR interfaces
- Interconnect and transceiver co-design, equalization
- Signal & power integrity issues
- Jitter, noise
- High-frequency interconnects, packages, antennas-in-package
- Novel/unconventional interconnect technologies

Manufacturing and measurement

- Manufacturing, testing, reliability
- Measurement techniques

Packaging and integration

- Advanced packaging, 3D integration
- Heterogeneous integration
- Design of interconnects and packages
- Quantum systems: interconnection & packaging aspects

Modeling and simulation

- Modeling, simulation, computer-aided design
- Thermal, mechanical, multiphysics modeling
- ML and AI-based approaches to interconnect and packaging problems

General chair

Piero Triverio
University of Toronto

Co-chair

Wendem Beyene
Meta

Finance chair

Vaishnav Srinivas
Qualcomm

Awards & grants

- Best paper award
- Best student paper award
- Best poster paper award
- Best benchmark paper award
- Student travel grants

Important dates

Paper submission:

July 2nd, 2024

Acceptance:

End of July 2024

Sponsor registration:

August 6th, 2024

Early bird

registration:

September 6th, 2024

